

# Bill of Materials

TI DESIGNS

TIDM-HRTTRANSMITTER

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1	2	C1, C3	1800pF	CAP, CERM, 1800pF, 100V, +/-10%, CAP, CERM, 0.018uF, 100V, +/-10%, X7R, 0603	MuRata	GRM188R72A182KA01D		0603	
2	1	C2	0.018uF	CAP, CERM, 0.018uF, 100V, +/-10%, X7R, 0603	Kemet	C0603C183K1RACTU		0603	
3	2	C4, C6	2700pF	CAP, CERM, 2700pF, 100V, +/-10%, CAP, CERM, 0.027uF, 100V, +/-10%, X7R, 0603	MuRata	GRM188R72A272KA01D		0603	
4	1	C5	0.027uF	CAP, CERM, 0.027uF, 100V, +/-10%, X7R, 0603	Kemet	C0603C273K1RACTU		0603	
5	2	C7, C8	0.1uF	CAP, CERM, 0.1uF, 16V, +/-10%, Diode, Schottky, 40V, 0.35A, SOD-523	Kemet	C0603X104K4RACTU		0603	
6	2	D1, D2	0.65V	Diode, Schottky, 40V, 0.35A, SOD-523	Diodes Inc.	ZHCS350TA		SOD-523	
7	1	J1		40Pin Booster Pack Connection Terminal Block, 6A, 3.5mm Pitch, 4-Pos, TH	Major League Electroni	CRD-081413-A-T	-	40Pin BP	
8	1	J2		Header, 100mil, 2x1, Gold, TH	On-Shore Technology	ED555/4DS		TERM_BLK_ED555-4DS	
9	2	J3, J4		Header, 100mil, 2x1, Gold, TH	Samtec	TSW-102-07-G-S		TSW-102-07-G-S	
10	4	R1, R3, R9, R11	4.22k	RES, 4.22k ohm, 0.1%, 0.125W, 0805	Susumu Co Ltd	RG2012P-4221-B-T5		0805_HV	
11	1	R2	3.24k	RES, 3.24k ohm, 0.1%, 0.333W, 1206	TT Electronics/IRC	PFC-W1206R-12-3241-B		1206	
12	1	R4	10k	RES, 10k ohm, 1%, 0.125W, 0402	Vishay Dale	CRCW040210K0FKEDHP	-	0402	
13	5	R5, R6, R7, R8, R10	0	RES, 0 ohm, 5%, 0.063W, 0402	Vishay-Dale	CRCW04020000Z0ED		0402	
14	1	U1		Low-Power, Low-Noise, 24-Bit ADC	Texas Instruments	ADS1220IRVAR		RVA16	

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